

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5977065

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MIN-TSE LEE	12/31/2019
SHENG-YEN CHENG	12/31/2019
YUEH-HUNG CHUNG	12/31/2019
KUANG-HSIANG LIAO	01/02/2020
YANG-CHUN LEE	02/11/2020
YAN-KAI WANG	01/02/2020
YA-LING HSU	12/25/2019
YI-REN CHEN	02/11/2020
HUNG-CHE LIN	12/30/2019
SHENG-JU HO	01/02/2020
CHIEN-HUANG LIAO	12/31/2019
CHEN-HSIEN LIAO	12/31/2019
RECEIVING PARTY DATA	
Name:	AU OPTRONICS CORPORATION
Street Address:	NO. 1, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK,
City:	HSINCHU
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16792904
CORRESPONDENCE DATA	
Fax Number:	(949)391-4699
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	886223692800
Email:	usa@jcipgroup.com
Correspondent Name:	JCIPRNET
Address Line 1:	8F-1, NO. 100, ROOSEVELT RD. SEC. 2,
Address Line 4:	TAIPEI CITY, TAIWAN 10084

ATTORNEY DOCKET NUMBER:	089969-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	02/24/2020
Total Attachments: 8 source=089969_dcl_assgn#page1.tif source=089969_dcl_assgn#page2.tif source=089969_dcl_assgn#page3.tif source=089969_dcl_assgn#page4.tif source=089969_dcl_assgn#page5.tif source=089969_dcl_assgn#page6.tif source=089969_dcl_assgn#page7.tif source=089969_dcl_assgn#page8.tif	

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

PIXEL ARRAY SUBSTRATE AND DRIVING METHOD THEREOF

As a below named inventor (hereinafter designated as the undersigned), I hereby
declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number

Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in
the application.

The undersigned hereby acknowledge that any willful false statement made in this
declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more
than five (5) years, or both.

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Au Optonics Corporation
of No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Min Tse Lee Date: 2019/12/31

Legal Name of Sole or First Inventor: **Min-Tse Lee**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Sheng Yen Cheng Date: 2019/12/31

Legal Name of Additional Joint Inventor, if any: **Sheng-Yen Cheng**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Yueh-Hung Chung Date: 2019/12/31

Legal Name of Additional Joint Inventor, if any: **Yueh-Hung Chung**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Kuang-Hsiang Liao**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Yang-Chun Lee**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

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DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: _____ Date: _____

Legal Name of Sole or First Inventor: **Min-Tse Lee**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Sheng-Yen Cheng**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Yueh-Hung Chung**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Kuang-Hsiang, Liao Date: 2020/01/02

Legal Name of Additional Joint Inventor, if any: **Kuang-Hsiang Liao**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Yang-Chun Lee**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: _____ Date: _____

Legal Name of Sole or First Inventor: **Min-Tse Lee**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Sheng-Yen Cheng**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Yueh-Hung Chung**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Kuang-Hsiang Liao**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Yang-Chun Lee Date: 2020.2.11

Legal Name of Additional Joint Inventor, if any: **Yang-Chun Lee**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

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**DECLARATION AND ASSIGNMENT
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Signature: Yan-Kai Wang Date: 2020.1.2

Legal Name of Additional Joint Inventor, if any: **Yan-Kai Wang**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Ya-Ling Hsu Date: 2019.12.25

Legal Name of Additional Joint Inventor, if any: **Ya-Ling Hsu**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Yi-Ren Chen**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Hung-Che Lin Date: 2019.12.30

Legal Name of Additional Joint Inventor, if any: **Hung-Che Lin**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Sheng-Ju Ho Date: 2020.1.2

Legal Name of Additional Joint Inventor, if any: **Sheng-Ju Ho**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Yan-Kai Wang**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Ya-Ling Hsu**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Yi-Ren Chen Date: 2020.2.11

Legal Name of Additional Joint Inventor, if any: **Yi-Ren Chen**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Hung-Che Lin**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: _____ Date: _____

Legal Name of Additional Joint Inventor, if any: **Sheng-Ju Ho**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Chien-Huang, Liao Date: 2019/12/31

Legal Name of Additional Joint Inventor, if any: **Chien-Huang Liao**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: Chen-Hsien Liao Date: 2019/12/31

Legal Name of Additional Joint Inventor, if any: **Chen-Hsien Liao**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.